


MATERIAL DECLARATION SHEET



Material Number	CC453232A Series			
Product Line	Wound Chip Inductor			
Compliance Date	2023/2/7			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Core	Ferite	0.031	Iron oxide (Fe2O3)	1309-37-1	66.0%	18.60%	28.18%
				Nickel oxide (NiO)	1313-99-1	8.0%	2.25%	
				Zinc oxide (ZnO)	1314-13-2	22.0%	6.20%	
				Copper oxide(CuO)	1317-38-0	4.0%	1.13%	
2	Wire	Copper Wire	0.01	Copper(Cu)	7440-50-8	95.0%	8.64%	9.09%
				Polyesterimide	37317-16-1	5.0%	0.45%	
3	Terminal	Copper	0.01	Copper (Cu)	7440-50-8	95.0%	8.64%	9.09%
				Tin (Sn)	7440-31-5	5.0%	0.45%	
4	Adhesive	Epoxy	0.022	Bisphenol A diglycidyl ether	25068-38-6	0.72	14.40%	20.00%
				Polyacrylic acid; 2-Propenoic acid homopolymer; A	9003-01-4	0.01	0.20%	
				Titanium Dioxide	13463-67-7	0.02	0.40%	
				Silicon dioxide	14808-60-7	0.25	5.00%	
5	Molding Compound	Silica	0.007	silica	60676-86-0	69.0%	4.39%	6.36%

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				Antimony(III) oxide	1309-64-4	2.5%	0.16%	
				Formaldehyde, polymer with 2-(chloromethyl)oxirane and 2-methylphenol	29690-82-2	15.0%	0.95%	
				Phenol-Formaldehyde Resin	9003-35-4	10.0%	0.64%	
				Brominated epoxy resin	40039-93-8	2.5%	0.16%	
				Carbon black	1333-86-4	1.0%	0.06%	
6	Solder Wire	Tin	0.015	Tin (Sn)	7440-31-5	100.0%	13.64%	13.64%
7	Solder Bar	Tin	0.015	Tin (Sn)	7440-31-5	100.0%	13.64%	13.64%
		Total weight	0.11					

This Document was updated on: 2023/2/7

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.